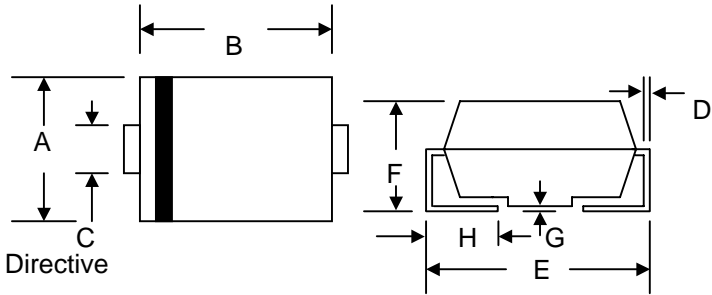


Features

- Schottky Barrier Chip
- Ideally Suited for Automatic Assembly
- Low Power Loss, High Efficiency
- Surge Overload Rating to 30A Peak
- For Use in Low Voltage Application
- Guard Ring Die Construction
- Plastic Case Material has UL Flammability Classification Rating 94V-O
- Green Products in Compliance with the RoHS Directive



Mechanical Data

- Case: Low Profile Molded Plastic
- Terminals: Solder Plated, Solderable per MIL-STD-750, Method 2026
- Polarity: Cathode Band or Cathode Notch
- Marking: Type Number
- Weight: 0.093 grams (approx.)

SMB/DO-214AA				
Dim	Min	Max	Min	Max
A	3.30	3.94	0.130	0.155
B	4.06	4.70	0.160	0.185
C	1.91	2.11	0.075	0.083
D	0.15	0.31	0.006	0.012
E	5.08	5.59	0.200	0.220
F	2.13	2.44	0.084	0.096
G	0.05	0.20	0.002	0.008
H	0.76	1.27	0.030	0.050
	In mm		In inch	

Maximum Ratings and Electrical Characteristics @ $T_A=25^\circ\text{C}$ unless otherwise specified

Characteristic	Symbol	SK12-G	SK13-G	SK14-G	SK15-G	SK16-G	SK18-G	SK19-G	S110-G	Unit
Peak Repetitive Reverse Voltage	V_{RRM}	20	30	40	50	60	80	90	100	V
Working Peak Reverse Voltage	V_{RWM}									
DC Blocking Voltage	V_R									
RMS Reverse Voltage	$V_{R(RMS)}$	14	21	28	35	42	56	64	71	V
Average Rectified Output Current @ $T_L = 75^\circ\text{C}$	I_O	1.0								A
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	30								A
Forward Voltage @ $I_F = 1.0\text{A}$	V_{FM}	0.55		0.70		0.85			V	
Peak Reverse Current @ $T_A = 25^\circ\text{C}$ At Rated DC Blocking Voltage @ $T_A = 100^\circ\text{C}$	I_{RM}					0.5				mA
						20				
Typical Thermal Resistance Junction to Ambient (Note 1)	$R_{\theta JA}$	95								K/W
Operating Temperature Range	T_j	-65 to +125								$^\circ\text{C}$
Storage Temperature Range	T_{STG}	-65 to +150								$^\circ\text{C}$

Note: 1. Mounted on P.C. Board with 5.0mm² copper pad areas

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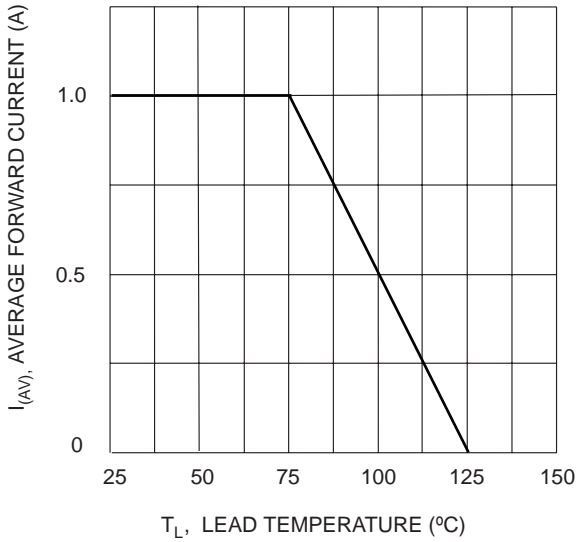


Fig. 1 Forward Current Derating Curve

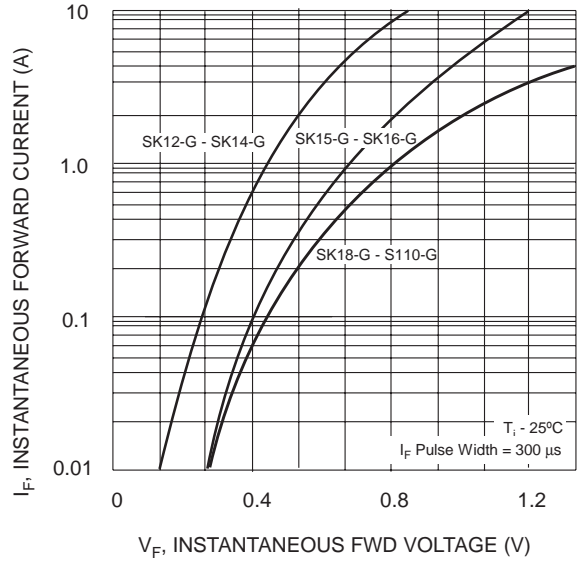


Fig. 2 Typ. Forward Characteristics

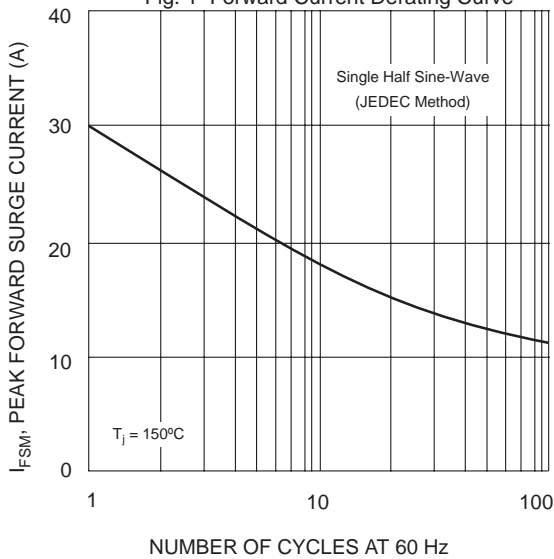


Fig. 3 Max Non-Repetitive Peak Fwd Surge Current

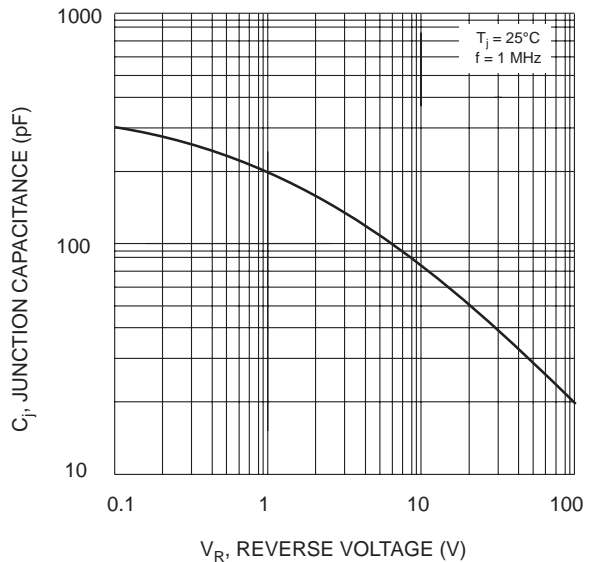


Fig. 4 Typical Junction Capacitance

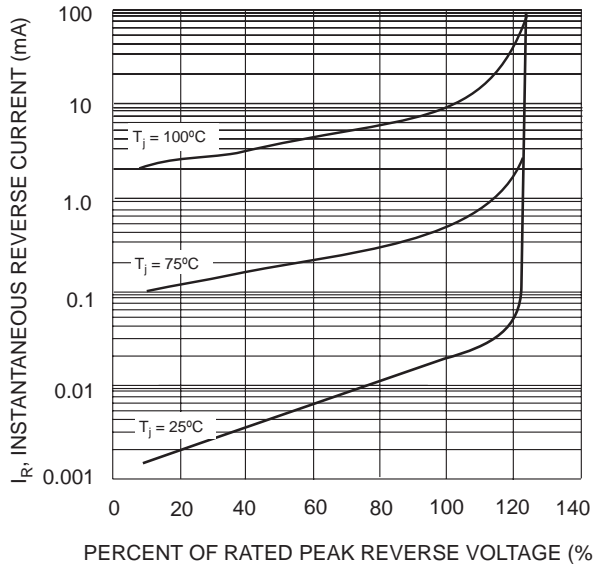


Fig. 5 Typical Reverse Characteristics

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